

## Description

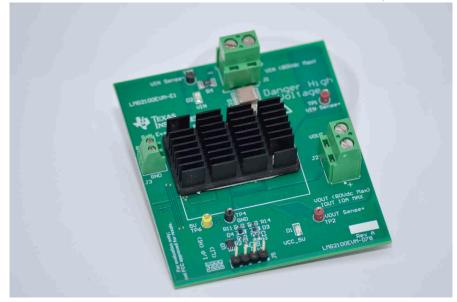
The LMG2100 evaluation module is a compact, easyto-use power stage with an external PWM signal. The board can be configured as a buck converter, boost converter, or other converter topology using a half bridge. Because this is an open-loop board with an external PWM signal, do not use to evaluate transient response. The device can be used to evaluate the performance of the LMG2100 as a hard-switched converter to sample measurements such as efficiency, switching speed and dv/dt (slew rate). The EVM features a LMG2100 half-bridge power module with two 100 V, 4.4-mΩ GaN FETs driven by 80-V GaN FET half-bridge gate driver. The module can deliver up to 20 A of current if the application includes adequate thermal management (monitor case temperature and verify adequate airflow is present if required). The thermal management considerations include forced air, heat sink, and lower operating frequency to minimize the power dissipation in the module.

## Features

- Input voltage operates up to 80 V DC
- Integrated 100-V, 4.4-m $\Omega$  GaN FETs with driver
- Open loop control with single or dual PWM signals
- Single-input, onboard for PWM signal with 8-ns dead time
- Configurable onboard dead-time adjustment by simple resistance change
- Onboard LDO for generating 5-V VCC supply from an unregulated supply between 5.5 V and 10 V
- Kelvin sense capability for efficiency
  measurements for input and output voltage
- Slew rate adjustment using series resistors along with C<sub>boot</sub> and C<sub>vcc</sub>

## Applications

- · High-speed synchronous buck/boost converters
- Solar power optimizer, Micro-inverter
- Class D amplifiers for audio
- · 48-V point-of-load converters for industrial
- Motor drives
- Power tools
- Telecom and server power



LMG2100EVM-078 Evaluation Module with Heat Sink

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# **1 Evaluation Module Overview**

## 1.1 Introduction

The LMG2100 device is an 100-V Gallium Nitride (GaN) half-bridge power module with an integrated driver. The device provides an integrated power stage using enhancement-mode GaN FETs. The LMG2100 device consists of two GaN FETs driven by one high-frequency GaN FET driver in a half-bridge configuration. The guide shows a circuit and the list of materials describing how to power the board up and how to set the board up for a certain regulation voltage. The EVM board is designed to accelerate the evaluation of the LMG2100. This board is not intended to be used as a standalone product, but is intended to evaluate the switching performance of LMG2100.

This evaluation module can be configured to either buck or boost mode by providing external gate signals. External heat sink is used to test this module up to 500W. External supply voltage (5.5 V to 10 V) is required to power the LMG2100 and dead time generation circuit.

## **1.2 Kit Contents**

The kit contains the following:

- Safety instructions
- LMG2100EVM-078 Circuit Board

## **1.3 Specification**

Parameter	Specifications		
Vin: Input voltage	0 V to 80 V		
Vout: Output voltage	0 V to 80 V		
Vcc: Input supply voltage	5.5 V to 10 V		
Maximum power	500W		
Switching frequency	100 kHz to 500 kHz		
Board dimensions	61 mm x 68 mm x 15 mm		

## **1.4 Device Information**

The LMG2100 device is an 80-V continuous, 100-V pulsed, 35-A half-bridge power stage, with integrated gatedriver and enhancement-mode Gallium Nitride (GaN) FETs. The device consists of two 100-V GaN FETs driven by one high-frequency 80-V GaN FET driver in a half-bridge configuration. The device extends advantages of discrete GaN FETs by offering a more user-friendly interface. This offers an excellent choice for high-frequency, high power density, and efficient power conversion.

The LMG2100 is available in a 5.5 mm x 4.5 mm x 0.89 mm lead-free QFN package with exposed die on the top side for cooling. Power pins of the device are optimized to accommodate easy PCB layout to achieve smaller power loop. The device supports 3.3-V, 5-V and 12-V input logic levels for the gate signals.

# 2 Hardware General Texas Instruments High Voltage Evaluation (TI HV EVM) User Safety Guidelines



Always follow TI's set-up and application instructions, including use of all interface components within their recommended electrical rated voltage and power limits. Always use electrical safety precautions to help ensure your personal safety and those working around you. Contact TI's Product Information Center http://ti.com/customer support for further information.

### Save all warnings and instructions for future reference.

#### WARNING

Failure to follow warnings and instructions can result in personal injury, property damage or death due to electrical shock and burn hazards.

The term TI HV EVM refers to an electronic device typically provided as an open framed, unenclosed printed circuit board assembly. It is *intended strictly for use in development laboratory environments, solely for qualified professional users having training, expertise and knowledge of electrical safety risks in development and application of high voltage electrical circuits. Any other use and/or application are strictly prohibited by Texas Instruments.* If you are not suitably qualified, then immediately stop from further use of the HV EVM.

- 1. Work Area Safety:
  - a. Keep work area clean and orderly.
  - b. Qualified observers must be present anytime circuits are energized.
  - c. Effective barriers and signage must be present in the area where the TI HV EVM and the interface electronics are energized, indicating operation of accessible high voltages can be present, for the purpose of protecting inadvertent access.
  - d. All interface circuits, power supplies, evaluation modules, instruments, meters, scopes, and other related apparatus used in a development environment exceeding 50Vrms/75VDC must be electrically located within a protected Emergency Power Off EPO protected power strip.
  - e. Use stable and non-conductive work surface.
  - f. Use adequately insulated clamps and wires to attach measurement probes and instruments. No freehand testing whenever possible.
- 2. Electrical Safety:
  - a. As a precautionary measure, a good engineering practice is to assume that the entire EVM has fully accessible and active high voltages.
  - b. De-energize the TI HV EVM and all the inputs, outputs and electrical loads before performing any electrical or other diagnostic measurements. Revalidate that TI HV EVM power has been safely deenergized.
  - c. With the EVM confirmed de-energized, proceed with required electrical circuit configurations, wiring, measurement equipment hook-ups and other application needs, while still assuming the EVM circuit and measuring instruments are electrically live.
  - d. Once EVM readiness is complete, energize the EVM as intended.

### WARNING

While the EVM is energized, never touch the EVM or the electrical circuits, as the ciruits can be at high voltages capable of causing electrical shock hazard.

### 3. Personal Safety

a. Wear personal protective equipment e.g. latex gloves or safety glasses with side shields or protect EVM in an adequate lucent plastic box with interlocks from accidental touch.

### Limitation for safe use:

EVMs are not to be used as all or part of a production unit.

## 2.1 Test Points

TEST POINT	DESCRIPTION
TP1	Sense connection for the input supply
TP2	Sense connection for output voltage
TP3	Sense connection for output ground
TP4	Analog Ground sense connection
TP6	5-V sense connection for LDO output
TP7	Sense connection for the input supply ground
J12	SW node, designed for use with oscilloscope probe and spring-type ground connection for better measurements
J1	VIN power connector (80-V DC maximum)
J2	VOUT power connector (80-V DC maximum)
J3	EXTVCC connection (5.5 V – 10 V)

### 2.1.1 Key Connections

The following test procedure is recommended primarily for powering up and shutting down the evaluation module. Never leave a powered EVM unattended for any length of time. Also, the unit must never be handled while power is applied.

## WARNING

There are high voltages present on the EVM. Some components reach temperatures above 50°C. Precautions must be taken when handling the board.

## 2.1.1.1 Connect a Supply to J3 Connector

There is the bias supply EXTVCC (between 5.5 V and 10 V) for the LMG2100 driver. This driver supply is regulated to 5 V by the series LDO U2 (LP3869). This regulation verifies that the bias supply for the LMG2100 is accurate and is not exceeded beyond the gate voltage specifications. This user's guide refers to this supply as the driver bias supply.

### 2.1.1.2 PWM Input

Provide the PWM input using a function generator that is capable of providing the desired switching frequency and duty cycle. This function generator output (0-5V signal) must be connected to the J5 connector as shown in the Figure 2-1. The left-most pin (pin 4) in this view is the positive input of the PWM supply and the remaining three pins are connected to GND in the default assembly for the board. The combination of R14-C22 and R2-C35 generates 8 ns to 10 ns of dead time.

Alternatively, two separate PWM inputs can be applied to control HI and LI independently. To apply this type of control, R11 must be removed, R13 must be populated with a  $0-\Omega$  resistor, and R12 must be replaced with a  $10-k\Omega$  resistor. On a board with these modifications, the HI signal must be applied at pin 4 of J5, and the LI signal at pin 2 of J5. Note that with this control scheme, the EVM no longer generates a dead time separating HI and LI transitions. Therefore, careful consideration must be applied to the control signals in this mode of operation to prevent a shoot-through condition. TI recommends to provide at least 8 ns of dead time through the external PWM signals.



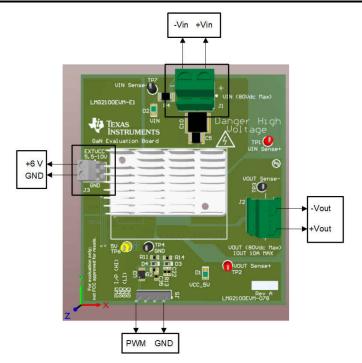


Figure 2-1. PWM Connection on J5

## 2.1.1.3 J1 Connector: Power Supply

Connect the input voltage to the J1 connector and verify that the positive and negative supply is connected appropriately. The positive and negative terminals are marked on the board. The sense connection for the input supply is through the TP1 and TP7 test points, respectively. This is useful when doing efficiency calculations as this verifies that the resistive losses to the board are taken into account and the losses calculated are related to the board and the LMG2100 half bridge.

The output load is connected to the J2 connector. The positive and negative sense signals are TP2 and TP3, respectively.

## 2.2 Power-Up Procedure

### 2.2.1 Step 1: Driver Bias Supply

Power up the driver bias supply (5.5 V to 10 V) first. The D1 diode lights up after the driver bias supply comes up. After this step, observe the PWM signals on test points TP9 and TP10. Verify that the PWM signal for the high and low side are of the desired frequency (100 kHz to 5 MHz depending on the input voltage and load). Also observe the default dead time between the high-to-low and low-to-high PWM transitions.

### 2.2.2 Step 2: Input Supply

Power up the input supply (10 V to 80 V). The D2 diode lights up after the input supply is powered up.

Observe the output voltage on the sense signals (TP2, TP3). Adjust the PWM duty cycle such that the output is of the desired voltage. Load the output with an appropriate electronic load.

#### Note

The PWM duty cycle must be adjusted to compensate for the losses when the supply is loaded

## 2.2.3 Step 3: Measure SW Voltage

To observe the SW node, connect a probe with a small pigtail to the via next to the SW pin, as shown in Measuring the SW Node. This verifies that the measurement loop is small and, hence, accurately reflects the behavior of the SW node. If a large loop is used, due to the high dv/dt on the SW node and the parasitic impedance (inductance) of the loop, then a large amount of ringing is observed on the SW node measurements. This ringing is not representative of the device performance, but is rather a measurement artifact. The probe connection must be made prior to the board being powered up and one must verify that appropriate safety precautions are taken.

Connect the scope probe to measure the SW node as shown in Figure 2-2. Notice the small pigtail used to minimize the ground loop.

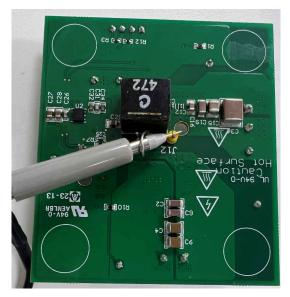


Figure 2-2. Measuring the SW Node

### 2.2.4 Setting Dead-Time

Dead times are set by the RC delays between the inverted and noninverted PWM input connected to jumper J3. The dead time typically does not require to be changed, however to evaluate impact of dead time on efficiency, the user can vary the RC delay. Changing the resistors R14 and R2 to get the appropriate dead time does not take much time. Verify that the dead time is not reduced too much to causes a shoot-through condition.

### 2.3 Power-Down Procedure

To power down the board, the power-up procedures must be followed in reverse.

- 1. The load must be turned off first.
- 2. Next, turn off the input supply.
- 3. The PWM signal must be turned off next.
- 4. Finally, turn off the driver bias supply.



## 2.4 Assembly Guidelines

Please follow the recommended assembly guidelines for the LMG2100 samples:

- Use low temperature solder paste (like Sn42-Bi58) whose melting temperature is around 130°C-140°C.
- Soldering using bottom side heating:
  - Recommended for thinner board (less than or equal to four layers) with no components directly underneath the device.
  - Place the solder paste as per the stencil recommendation given in the data sheet.
  - Board held on a pedestal at around 2-3 cm from the top of the hot air blower and device is aligned to keep on the footprint.
- Soldering using top side heating:
  - This method is recommended for thicker board (more than 4 layers).
  - Use hot air gun (with temperature set to 400°C) and blow the air around the device avoiding directly above the device (temperature can be higher but used for shorter duration).
- Look for proper soldering connection of signal pins. If there are excess solder, then please remove them manually using solder iron.
- Avoid putting excess solder paste especially near the edge of PGND pad (pin number 6).
- If the assembly is done through automatic reflow oven, then set the temperature to less than 180°C.

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## **3 Implementation Results**

## 3.1 Electrical Performance Specifications

The inductor used in this EVM is a 4.7- $\mu$ H inductor which is rated for 25A. There are chances of heating up this inductor if operated at higher switching frequency and higher current level. Please monitor the temperature of the inductor and add external fan cooling if necessary. The switching frequency is set by an external PWM signal (between 0 V and 5 V). The duty cycle of this PWM signal sets the duty cycle of the half-bridge module.

## 3.1.1 Evaluation Setup

This section describes the EVM hardware and outlines the procedure to set up for evaluation. Figure 3-1 and Figure 3-2 show the top and bottom views of the LMG21EVM-078, respectively.





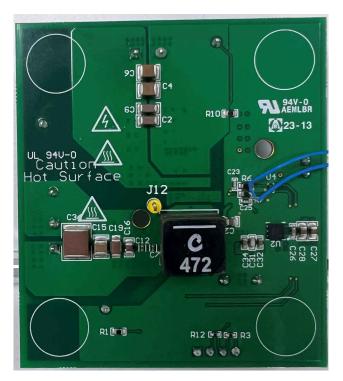


Figure 3-2. LMG2100EVM-078 Board (Bottom View)

The EVM can be mounted with a heat sink (S05MZZ37, 20 mm x 35 mm x 10 mm) to improve the thermal performance. The two exposed thermal pads have a high-voltage potential difference between them, therefore an electrically isolated thermal interface material (TIM) is used. TIM of GR80A-0H-50GY (thermal conductivity of 8 W/mK and thickness of 0.5 mm) has been placed between the device and the heat sink.

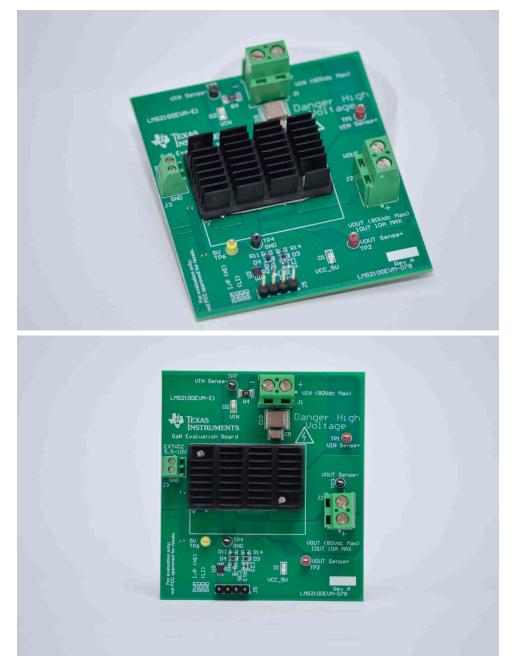


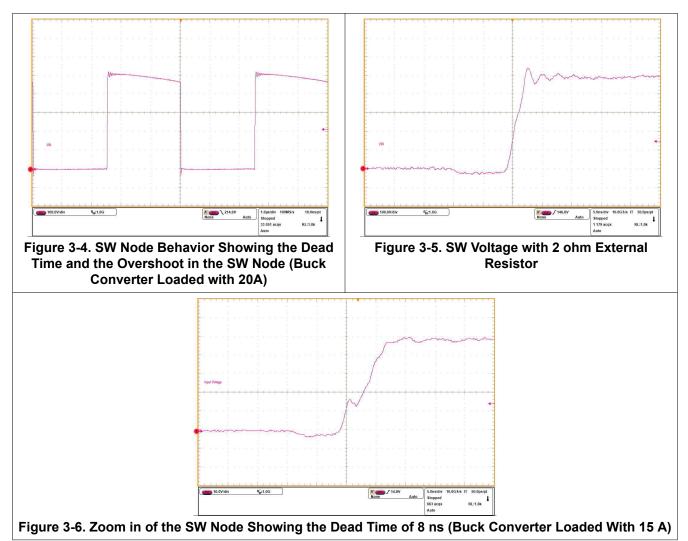
Figure 3-3. Evaluation Module with Heat Sink

## WARNING

High voltages that can cause injury exist on this evaluation module (EVM). Please verify all safety procedures are followed when working on this EVM. Never leave a powered EVM unattended.



## 3.1.2 Performance Data and Results



Note

Visit the E2E forum Gallium Nitride Solutions for more information regarding LMG2100 or LMG2100 hard-switched EVM.



## **4 Hardware Design Files**

## 4.1 Schematic

Figure 4-1 shows the schematic of the EVM.

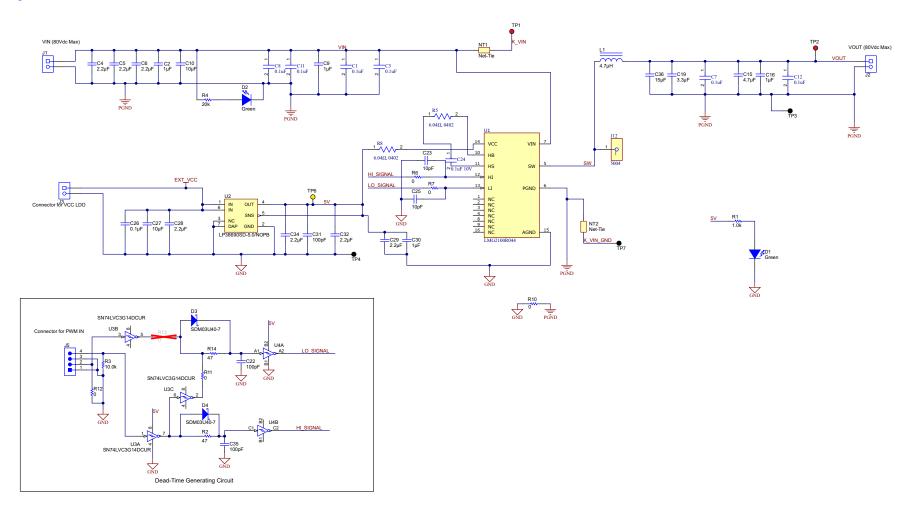


Figure 4-1. LMG2100EVM-078 Schematic



## 4.2 PCB Layouts

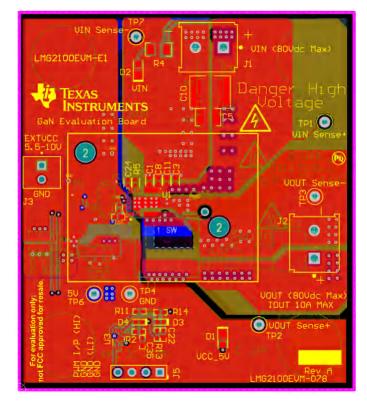


Figure 4-2. Top Layer of the PCB

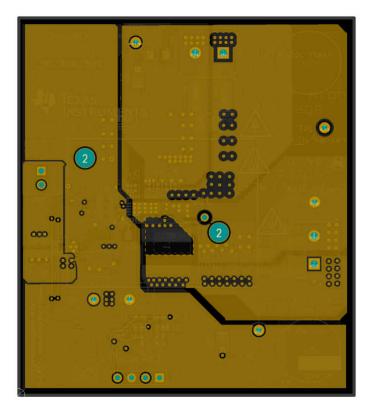


Figure 4-3. Mid Layer-1 showing return path for power loop



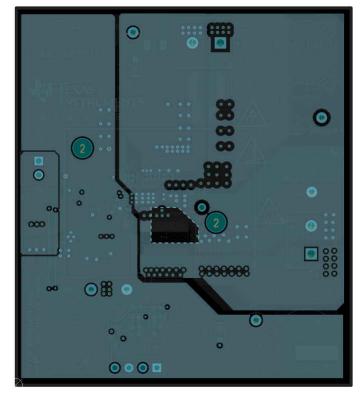


Figure 4-4. Mid Layer-2

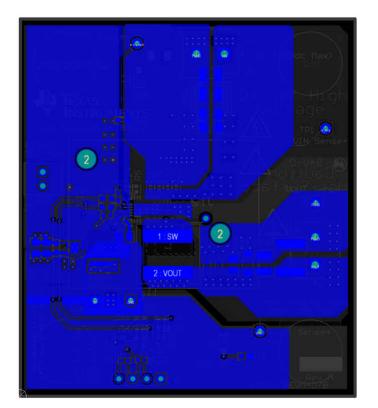


Figure 4-5. Bottom Layer

## 4.3 Bill of Materials

## Table 4-1. LMG2100EVM-078 Bill of Materials<sup>(2)</sup>

DESIGNATOR	QTY	VALUE	DESCRIPTION	PACKAGE REFERENCE	PART NUMBER	MANUFACTURER
PCB1	1		Printed-Circuit Board			Any
C1, C3, C7, C8, C11, C12	6	0.1uF	CAP, CERM, 0.1uF, 100 V, +/-10%, X7R, 0402	0402	GRM155R62A104KE14D	MuRata
C2, C9	2	1uF	CAP, CERM, 1uF, 100 V, +/-20%, X7R, 1206	1206	C3216X7R2A105M160AA	ТDК
C4, C5, C6	3	2.2uF	CAP, CERM, 2.2 μF, 100 V, +/- 10%, X7R, 1210	1210	GRM32ER72A225KA35L	MuRata
C10	1	10uF	CAP, CERM, 10 µF, 100 V, +/- 20%, X7R, 2220	2220	22201C106MAT2A	AVX
C15	2	4.7uF	CAP, CERM, 4.7 μF, 100 V, +/- 10%, X7S, 1210	1210	C3225X7S2A475K200AE	TDK
C16	1	1uF	CAP, CERM, 1 μF, 100 V, +/- 10%, X7S, 0805	0805	C2012X7S2A105K125AB	TDK
C19	1	3.3uF	CAP, CERM, 3.3 µF, 100 V, +/- 20%, X7S, 1206_190	1206_190	C3216X7S2A335M160AB	TDK
C22, C35	2	100 pF	CAP, CERM, 100 pF, 50 V, +/-5%, C0G/NP0, 0402	0402	CC0402JRNPO9BN101	Yageo America
C23, C25	2	10 pF	CAP, CERM, 10 pF, 50 V, +/-5%, C0G/NP0, 0402	0402	GRM1555C1H100JA01D	MuRata
C24	1	0.1uF	CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	0402	0402ZD104KAT4A	TDK
C26	1	0.1uF	CAP, CERM, 0.1 µF, 16 V, +/- 5%, X7R, 0603	0603	0603YC104JAT2A	AVX
C27	1	10uF	CAP, CERM, 10uF, 25 V, +/-10%, X5R, 0805	0805	C2012X5R1E106K125AB	ТDК
C28, C29	2	2.2uF	CAP, CERM, 2.2uF, 16 V, +/-10%, X7R, 0805	0805	C0805C225K4RACTU	Kemet
C30	1	1uF	CAP, CERM, 1uF, 25 V, +/-10%, X5R, 0402	0402	C1005X5R1E105K050BC	ТDК
C31	1	100 pF	CAP, CERM, 100 pF, 25 V, +/-10%, X7R, 0603	0603	06033C101KAT2A	AVX
C32, C34	2	2.2uF	CAP, CERM, 2.2uF, 10 V, +/-10%, X7R, 0603	0603	GRM188R71A225KE15D	MuRata
C36	1	15uF	CAP, CERM, 15 µF, 100 V, +/- 20%, X7S, 2220	2220	C5750X7S2A156M250KB	ТDК
D1, D2	2	Green	LED, Green, SMD	LED_0805	LTST-C170KGKT	Lite-On
D3, D4	2	40 V	Diode, Schottky, 40 V, 0.03A, SOD-523	SOD-523	SDM03U40-7	Diodes Inc.
H1	1		Heatsink	20x35x10 mm	S05MZZ37	Alpha Novatech
H2	1		TIM	0.5 mm	GR80A-0H-50GY	Fujipoly
J1, J2	2		Terminal Block, 2x1, 5.08mm, TH	10.16x15.2x9mm	282841-2	TE Connectivity
J3	1		Terminal Block, 2x1, 2.54mm, TH	Terminal Block, 2x1, 2.54mm, TH	282834-2	TE Connectivity
J5	1		Header, 100mil, 4x1, Tin, TH	Header, 4x1, 100mil, TH	5-146278-4	TE Connectivity
J12	1		PC Test point mini			
L1	1	4.7uH	Inductor, Shielded, Composite, 4.7 μH, 25.4 A, 0.0057 ohm, SMD	10 x 10 x 11.3mm	XAL1010-472MED	Coilcraft
R1	1	1.0k	RES, 1.0k ohm, 5%, 0.1W, 0603	0603	CRCW06031K00JNEA	Vishay-Dale



DESIGNATOR	QTY	VALUE	DESCRIPTION	PACKAGE REFERENCE	PART NUMBER	MANUFACTURER
R2, R14	2	47	RES, 47 ohm, 5%, 0.063W, 0402	0402	CRCW040247R0JNED	Vishay-Dale
R3	1	10.0k	RES, 10.0k ohm, 1%, 0.063W, 0402	0402	CRCW040210K0FKED	Vishay-Dale
R4	1	20k	RES, 20k ohm, 5%, 0.25W, 1206	1206	CRCW120620K0JNEA	Vishay-Dale
R5, R8	2	6.04	RES, 6.04 ohm, 1%, 0.063W, 0402	0402	CRCW04026R04FKED	Vishay-Dale
R6, R7, R10	3	0	RES, 0 ohm, 5%, 0.1W, 0603	0603	CRCW06030000Z0EA	Vishay-Dale
R11, R12	2	0	RES, 0 ohm, 5%, 0.063W, 0402	0402	CRCW04020000Z0ED	Vishay-Dale
R13	1	0	RES, 0 ohm, 5%, 0.063W, 0402	0402	CRCW04020000Z0ED	Vishay-Dale
TP1, TP2	2	Red	Test Point, Miniature, Red, TH	Red Miniature Testpoint	5000	Keystone
TP3, TP4, TP7	3	Black	Test Point, Miniature, Black, TH	Black Miniature Testpoint	5001	Keystone
TP6	1		Test Point, Miniature, Yellow, TH	Yellow Miniature Testpoint	5004	Keystone
U1	1		80 V, 19 A GaN Half-Bridge Power Stage	MOF0009A	LMG2100RO44	Texas Instruments <sup>(1)</sup>
U2	1		1 A Low Dropout CMOS Linear Regulators Stable with Ceramic Output Capacitors, 6- pin LLP, Pb-Free	SDE06A	LP38690SD-5.0/NOPB	Texas Instruments <sup>(1)</sup>
U3	1		Triple Schmitt-Trigger Inverter, DCU0008A	DCU0008A	SN74LVC3G14DCUR	Texas Instruments <sup>(1)</sup>
U4	1		Dual Schmitt-Trigger Inverter, YZP0006ADBD (DSBGA-6)	YZP0006ADBD	SN74LVC2G14YZPR	Texas Instruments <sup>(1)</sup>

Table 4-1. LMG2100EVM-078 Bill of Materials<sup>(2)</sup> (continued)

(1) No alternate component manufacturer.

(2) Unless otherwise noted, all parts can be substituted with equivalents.

## **5** Additional Information

## 5.1 Trademarks

All trademarks are the property of their respective owners.

#### STANDARD TERMS FOR EVALUATION MODULES

- 1. Delivery: TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, and/or documentation which may be provided together or separately (collectively, an "EVM" or "EVMs") to the User ("User") in accordance with the terms set forth herein. User's acceptance of the EVM is expressly subject to the following terms.
  - 1.1 EVMs are intended solely for product or software developers for use in a research and development setting to facilitate feasibility evaluation, experimentation, or scientific analysis of TI semiconductors products. EVMs have no direct function and are not finished products. EVMs shall not be directly or indirectly assembled as a part or subassembly in any finished product. For clarification, any software or software tools provided with the EVM ("Software") shall not be subject to the terms and conditions set forth herein but rather shall be subject to the applicable terms that accompany such Software
  - 1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.
- 2 Limited Warranty and Related Remedies/Disclaimers:
  - 2.1 These terms do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.
  - 2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for a nonconforming EVM if (a) the nonconformity was caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI, (b) the nonconformity resulted from User's design, specifications or instructions for such EVMs or improper system design, or (c) User has not paid on time. Testing and other quality control techniques are used to the extent TI deems necessary. TI does not test all parameters of each EVM. User's claims against TI under this Section 2 are void if User fails to notify TI of any apparent defects in the EVMs within ten (10) business days after delivery, or of any hidden defects with ten (10) business days after the defect has been detected.
  - 2.3 TI's sole liability shall be at its option to repair or replace EVMs that fail to conform to the warranty set forth above, or credit User's account for such EVM. TI's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.

## WARNING

Evaluation Kits are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems.

User shall operate the Evaluation Kit within TI's recommended guidelines and any applicable legal or environmental requirements as well as reasonable and customary safeguards. Failure to set up and/or operate the Evaluation Kit within TI's recommended guidelines may result in personal injury or death or property damage. Proper set up entails following TI's instructions for electrical ratings of interface circuits such as input, output and electrical loads.

NOTE:

EXPOSURE TO ELECTROSTATIC DISCHARGE (ESD) MAY CAUSE DEGREDATION OR FAILURE OF THE EVALUATION KIT; TI RECOMMENDS STORAGE OF THE EVALUATION KIT IN A PROTECTIVE ESD BAG.

3 Regulatory Notices:

3.1 United States

3.1.1 Notice applicable to EVMs not FCC-Approved:

**FCC NOTICE:** This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.

3.1.2 For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:

#### CAUTION

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

#### FCC Interference Statement for Class A EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

#### FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.
- 3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210 or RSS-247

#### Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSSs. Operation is subject to the following two conditions:

(1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

#### Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

#### **Concerning EVMs Including Detachable Antennas:**

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

#### Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur

- 3.3 Japan
  - 3.3.1 Notice for EVMs delivered in Japan: Please see http://www.tij.co.jp/lsds/ti\_ja/general/eStore/notice\_01.page 日本国内に 輸入される評価用キット、ボードについては、次のところをご覧ください。

https://www.ti.com/ja-jp/legal/notice-for-evaluation-kits-delivered-in-japan.html

3.3.2 Notice for Users of EVMs Considered "Radio Frequency Products" in Japan: EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, not certified to Technical Regulations of Radio Law of Japan, User is required to follow the instructions set forth by Radio Law of Japan, which includes, but is not limited to, the instructions below with respect to EVMs (which for the avoidance of doubt are stated strictly for convenience and should be verified by User):

- 1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
- 2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
- 3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

【無線電波を送信する製品の開発キットをお使いになる際の注意事項】 開発キットの中には技術基準適合証明を受けて

いないものがあります。 技術適合証明を受けていないもののご使用に際しては、電波法遵守のため、以下のいずれかの 措置を取っていただく必要がありますのでご注意ください。

- 1. 電波法施行規則第6条第1項第1号に基づく平成18年3月28日総務省告示第173号で定められた電波暗室等の試験設備でご使用 いただく。
- 2. 実験局の免許を取得後ご使用いただく。
- 3. 技術基準適合証明を取得後ご使用いただく。
- なお、本製品は、上記の「ご使用にあたっての注意」を譲渡先、移転先に通知しない限り、譲渡、移転できないものとします。 上記を遵守頂けない場合は、電波法の罰則が適用される可能性があることをご留意ください。 日本テキサス・イ

ンスツルメンツ株式会社

#### 東京都新宿区西新宿6丁目24番1号

西新宿三井ビル

- 3.3.3 Notice for EVMs for Power Line Communication: Please see http://www.tij.co.jp/lsds/ti\_ja/general/eStore/notice\_02.page 電力線搬送波通信についての開発キットをお使いになる際の注意事項については、次のところをご覧くださ い。https://www.ti.com/ja-jp/legal/notice-for-evaluation-kits-for-power-line-communication.html
- 3.4 European Union
  - 3.4.1 For EVMs subject to EU Directive 2014/30/EU (Electromagnetic Compatibility Directive):

This is a class A product intended for use in environments other than domestic environments that are connected to a low-voltage power-supply network that supplies buildings used for domestic purposes. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures.

#### 4 EVM Use Restrictions and Warnings:

- 4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.
- 4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.
- 4.3 Safety-Related Warnings and Restrictions:
  - 4.3.1 User shall operate the EVM within TI's recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, even with the inputs and outputs kept within the specified allowable ranges, some circuit components may have elevated case temperatures. These components include but are not limited to linear regulators, switching transistors, pass transistors, current sense resistors, and heat sinks, which can be identified using the information in the associated documentation. When working with the EVM, please be aware that the EVM may become very warm.
  - 4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and inability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.
- 4.4 User assumes all responsibility and liability to determine whether the EVM is subject to any applicable international, federal, state, or local laws and regulations related to User's handling and use of the EVM and, if applicable, User assumes all responsibility and liability for compliance in all respects with such laws and regulations. User assumes all responsibility and liability for proper disposal and recycling of the EVM consistent with all applicable international, federal, state, and local requirements.
- 5. Accuracy of Information: To the extent TI provides information on the availability and function of EVMs, TI attempts to be as accurate as possible. However, TI does not warrant the accuracy of EVM descriptions, EVM availability or other information on its websites as accurate, complete, reliable, current, or error-free.
- 6. Disclaimers:
  - 6.1 EXCEPT AS SET FORTH ABOVE, EVMS AND ANY MATERIALS PROVIDED WITH THE EVM (INCLUDING, BUT NOT LIMITED TO, REFERENCE DESIGNS AND THE DESIGN OF THE EVM ITSELF) ARE PROVIDED "AS IS" AND "WITH ALL FAULTS." TI DISCLAIMS ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, REGARDING SUCH ITEMS, INCLUDING BUT NOT LIMITED TO ANY EPIDEMIC FAILURE WARRANTY OR IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF ANY THIRD PARTY PATENTS, COPYRIGHTS, TRADE SECRETS OR OTHER INTELLECTUAL PROPERTY RIGHTS.
  - 6.2 EXCEPT FOR THE LIMITED RIGHT TO USE THE EVM SET FORTH HEREIN, NOTHING IN THESE TERMS SHALL BE CONSTRUED AS GRANTING OR CONFERRING ANY RIGHTS BY LICENSE, PATENT, OR ANY OTHER INDUSTRIAL OR INTELLECTUAL PROPERTY RIGHT OF TI, ITS SUPPLIERS/LICENSORS OR ANY OTHER THIRD PARTY, TO USE THE EVM IN ANY FINISHED END-USER OR READY-TO-USE FINAL PRODUCT, OR FOR ANY INVENTION, DISCOVERY OR IMPROVEMENT, REGARDLESS OF WHEN MADE, CONCEIVED OR ACQUIRED.
- 7. USER'S INDEMNITY OBLIGATIONS AND REPRESENTATIONS. USER WILL DEFEND, INDEMNIFY AND HOLD TI, ITS LICENSORS AND THEIR REPRESENTATIVES HARMLESS FROM AND AGAINST ANY AND ALL CLAIMS, DAMAGES, LOSSES, EXPENSES, COSTS AND LIABILITIES (COLLECTIVELY, "CLAIMS") ARISING OUT OF OR IN CONNECTION WITH ANY HANDLING OR USE OF THE EVM THAT IS NOT IN ACCORDANCE WITH THESE TERMS. THIS OBLIGATION SHALL APPLY WHETHER CLAIMS ARISE UNDER STATUTE, REGULATION, OR THE LAW OF TORT, CONTRACT OR ANY OTHER LEGAL THEORY, AND EVEN IF THE EVM FAILS TO PERFORM AS DESCRIBED OR EXPECTED.

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- 8. Limitations on Damages and Liability:
  - 8.1 General Limitations. IN NO EVENT SHALL TI BE LIABLE FOR ANY SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL, OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF THESE TERMS OR THE USE OF THE EVMS, REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. EXCLUDED DAMAGES INCLUDE, BUT ARE NOT LIMITED TO, COST OF REMOVAL OR REINSTALLATION, ANCILLARY COSTS TO THE PROCUREMENT OF SUBSTITUTE GOODS OR SERVICES, RETESTING, OUTSIDE COMPUTER TIME, LABOR COSTS, LOSS OF GOODWILL, LOSS OF PROFITS, LOSS OF SAVINGS, LOSS OF USE, LOSS OF DATA, OR BUSINESS INTERRUPTION. NO CLAIM, SUIT OR ACTION SHALL BE BROUGHT AGAINST TI MORE THAN TWELVE (12) MONTHS AFTER THE EVENT THAT GAVE RISE TO THE CAUSE OF ACTION HAS OCCURRED.
  - 8.2 Specific Limitations. IN NO EVENT SHALL TI'S AGGREGATE LIABILITY FROM ANY USE OF AN EVM PROVIDED HEREUNDER, INCLUDING FROM ANY WARRANTY, INDEMITY OR OTHER OBLIGATION ARISING OUT OF OR IN CONNECTION WITH THESE TERMS, EXCEED THE TOTAL AMOUNT PAID TO TI BY USER FOR THE PARTICULAR EVM(S) AT ISSUE DURING THE PRIOR TWELVE (12) MONTHS WITH RESPECT TO WHICH LOSSES OR DAMAGES ARE CLAIMED. THE EXISTENCE OF MORE THAN ONE CLAIM SHALL NOT ENLARGE OR EXTEND THIS LIMIT.
- 9. Return Policy. Except as otherwise provided, TI does not offer any refunds, returns, or exchanges. Furthermore, no return of EVM(s) will be accepted if the package has been opened and no return of the EVM(s) will be accepted if they are damaged or otherwise not in a resalable condition. If User feels it has been incorrectly charged for the EVM(s) it ordered or that delivery violates the applicable order, User should contact TI. All refunds will be made in full within thirty (30) working days from the return of the components(s), excluding any postage or packaging costs.
- 10. Governing Law: These terms and conditions shall be governed by and interpreted in accordance with the laws of the State of Texas, without reference to conflict-of-laws principles. User agrees that non-exclusive jurisdiction for any dispute arising out of or relating to these terms and conditions lies within courts located in the State of Texas and consents to venue in Dallas County, Texas. Notwithstanding the foregoing, any judgment may be enforced in any United States or foreign court, and TI may seek injunctive relief in any United States or foreign court.

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